

### Self-powered nodes and Bio-Sensing

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Today's prototypes 2005 → 2006 → 2007

~2 inch

Temp.

Light sensor

1cm

MEMS version in progress

### Technology Platforms for Pervasive Computing

From a 'meso-scale' running at milliwatts

To a 'micro-scale' at  $\mu\text{W}$

Adapted from Various Sources:  
E.g. Ember, Crossbow, K. Pister, J. Rabaey, D. Culler...

2

### Design Question: What energy can one harvest in 1 cm<sup>3</sup>?

	$\mu\text{W}/\text{cm}^3$
Solar (outside)	15,000
Air flow	380
Human power	330
Vibration	200
Temperature	40
Pressure Var.	17
Solar (inside)	10

3

### Vibration-Based-Scavenging

Sources

- HVAC ducts
- Raised Floors
- Motors
- Large windows
- Mount under wooden staircase

◆Three Rules for Design

- $P \sim M$
- $P \sim A^2$
- $P \sim 1/\omega$



◆PZT-shims with W-mass

- Early work  $\sim 800 \mu\text{W}/\text{cm}^3$  at  $5 \text{ m/s}^2$  (on a clothes dryer!)



◆Recent successes

- TinyTemp Node on stairs
- MEMS piezo bender

4



## TinyTemp/TinyOS Node

- ◆ Stair-Case Vibrations from Running Up and Down Stairs
- ◆ Piezoelectric: PZT
- ◆ Tungsten Alloy Mass: 52 g
- ◆ Beam Dimensions:
  - ◆ 1.25" x 0.5" x 0.02"
  - ◆ Resonant Frequency: 26.8 Hz
  - ◆ Power Output: 450  $\mu$ W

PhD Research of Eli Leland, Elaine Lai, Jessy Baker

5






## "Most challenging issue"

- ◆ Reduction to MEMS
- ◆ Miniaturization while maintaining sufficient energy scavenging to power the next generation low power radios

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6





## Microfabrication

- ◆ Base layer of Si/STO ( $\text{SrTiO}_3$ ) provided by Motorola
  - ◆ Si provides ease of fabrication
  - ◆ STO enables epitaxial growth
- ◆ SRO ( $\text{SrRuO}_3$ ) PZT ( $\text{PbZr}_{0.53}\text{Ti}_{0.47}\text{O}_3$ ) deposited via PLD
  - ◆ 50 nm of SRO
  - ◆ 500 nm of PZT
  - ◆ 50 nm of SRO

Base layer (Silicon Wafer)

7

## Deposition and patterning

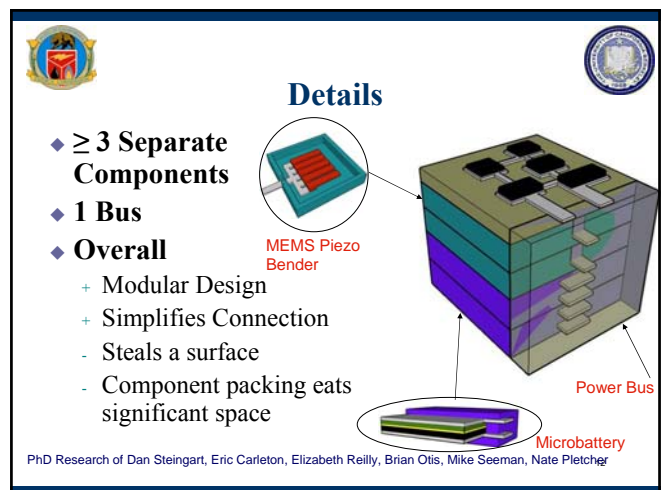
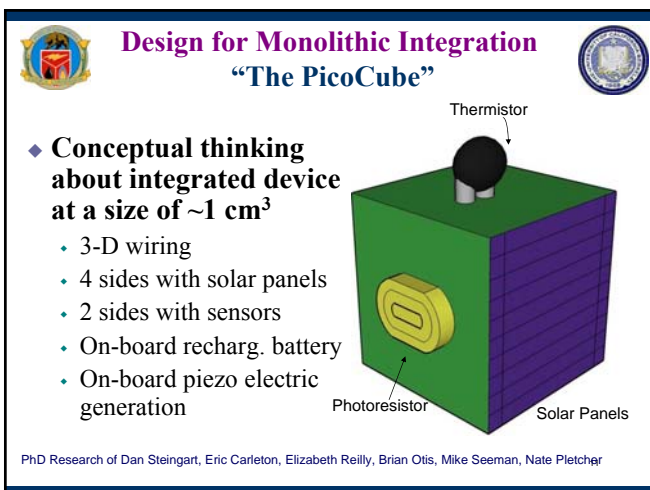
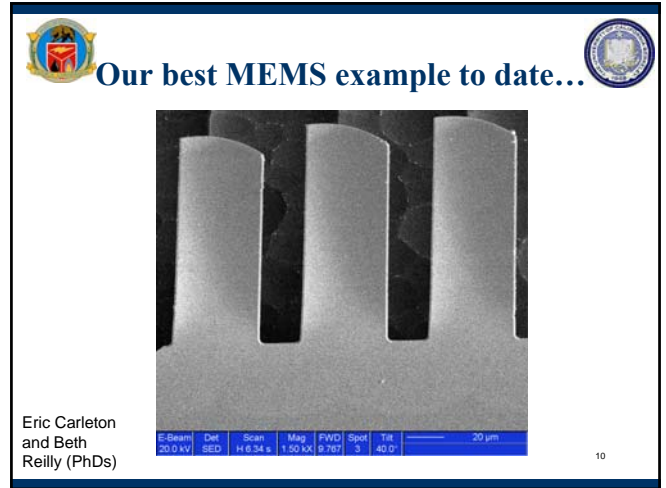
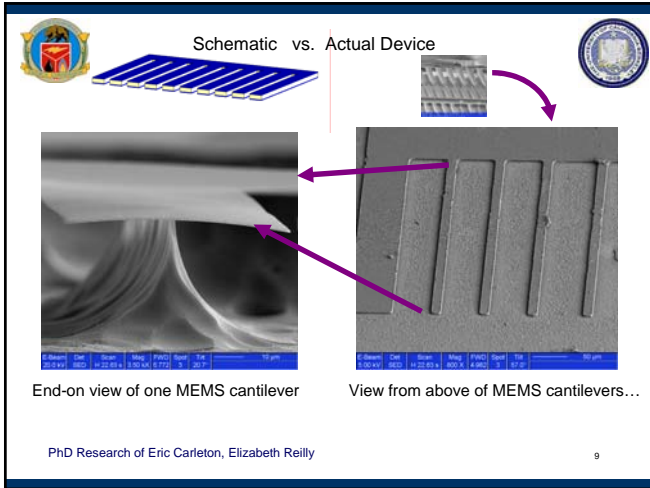
Edwards electron beam evaporator



- \* Ti: 10-15 nm (for adhesion purposes)
- \* Pt: 150-200 nm
- Pt thickness will be varied to function as elastic layer....

- ◆ Initial etching
  - Ar Ion mill
  - \* 5 nm/min @ 0.25 mA

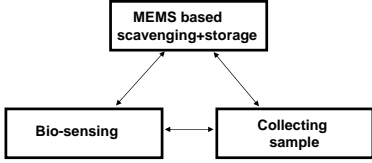
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8





## “Bio-Piconodes”



**Biosensor:**

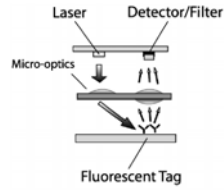
- Small, integrated, low-cost, low-power sensor
- Produces an electronic signal in proportion to an analyte (O<sub>2</sub>, glucose etc.) or local condition (pH, temperature etc.)

13

## Towards Low-Power Bio-Sensors

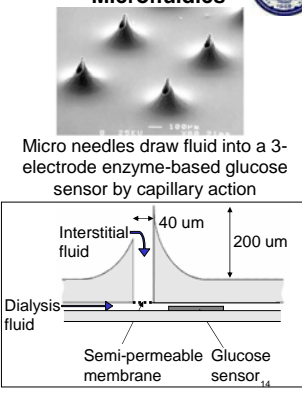
### Fluorescence Microscopy





At 2mW, the VCSEL (Vertical Cavity Surface Emitting Laser) produces 100nA signal for 100uM sample

STANFORD: Modified from Thrush, 2003

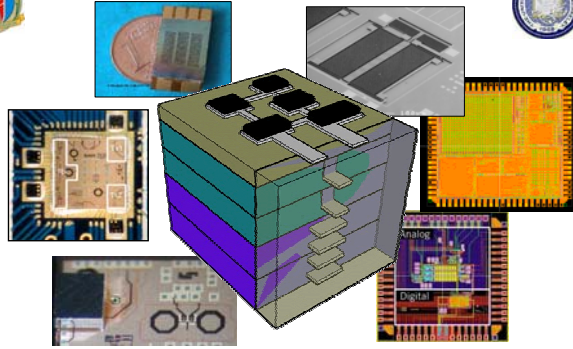
### Microfluidics



BERKELEY: Modified from Liepmann, 2003

## End/Summary/Questions



**Advanced 2.5 packaging: the answer to mm<sup>2</sup> nodes + the design trade-offs based on source, storage, duty-cycle, sensors**

P. Wright, Jan Rabaey, S. Sanders, James Evans  
Also: Infineon, Agilent

15